

Title (en)

Method for material removing machining of a wafer edge

Title (de)

Verfahren zur materialabtragenden Bearbeitung der Kante einer Halbleiterscheibe

Title (fr)

Procédé pour l'usinage par enlèvement de matière du bord d'une plaquette semi-conductrice

Publication

EP 0881035 B1 19991027 (DE)

Application

EP 97115333 A 19970904

Priority

DE 19636055 A 19960905

Abstract (en)

[origin: DE19636055A1] The semiconductor disc rests on a rotatable table, rotates about a centre axis, and is machined by several rotating tools, each of which removes a certain material amount from the disc edge. During the disc rotation the tools are sequentially moved against the disc edge for simultaneous machining. A tool, just fed into cut, removes less material from the edge than a previously cutting tool. The disc edge machining is not finished until the disc has been rotated through 360 deg . Pref. the tools are selected from a group contg. grinding and polishing tools and tools for ductile grinding.

IPC 1-7

B24B 9/06; **B24B 27/00**; **B24B 1/04**; **B24B 37/02**

IPC 8 full level

B24B 9/00 (2006.01); **B24B 1/04** (2006.01); **B24B 9/06** (2006.01); **B24B 27/00** (2006.01); **B24B 37/02** (2012.01); **H01L 21/304** (2006.01)

CPC (source: EP KR US)

B24B 1/04 (2013.01 - EP US); **B24B 9/065** (2013.01 - EP US); **B24B 27/0076** (2013.01 - EP US); **B24B 37/02** (2013.01 - EP US); **H01L 21/321** (2013.01 - KR)

Cited by

DE19928949A1

Designated contracting state (EPC)

DE GB IT

DOCDB simple family (publication)

DE 19636055 A1 19980312; DE 59700621 D1 19991202; EP 0881035 A1 19981202; EP 0881035 B1 19991027; JP 2900253 B2 19990602; JP H1080849 A 19980331; KR 100273960 B1 20010115; KR 19980024185 A 19980706; TW 352354 B 19990211; US 6045436 A 20000404

DOCDB simple family (application)

DE 19636055 A 19960905; DE 59700621 T 19970904; EP 97115333 A 19970904; JP 20034297 A 19970725; KR 19970041267 A 19970826; TW 86112483 A 19970901; US 90657397 A 19970805